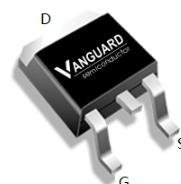


## Features

- N-Channel, 5V Logic Level Control
- Enhancement mode
- Very low on-resistance  $R_{DS(on)}$  @  $V_{GS}=4.5$  V
- Fast Switching
- 100% Avalanche test
- Pb-free lead plating; RoHS compliant

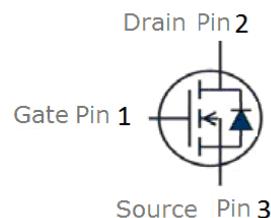
$V_{DS}$	60	V
$R_{DS(on),TYP}@ V_{GS}=10$ V	7	$m\Omega$
$R_{DS(on),TYP}@ V_{GS}=4.5$ V	8	$m\Omega$
$I_D$	65	A

TO-252



Halogen-Free

Part ID	Package Type	Marking	Tape and reel information
VS6065AD	TO-252	6065AD	2500PCS/Reel



## Maximum ratings, at $T_j=25^\circ C$ , unless otherwise specified

Symbol	Parameter	Rating	Unit
$V_{(BR)DSS}$	Drain-Source breakdown voltage	60	V
$I_s$	Diode continuous forward current	$T_c=25^\circ C$	A
$I_D$	Continuous drain current@ $V_{GS}=10V$	$T_c=25^\circ C$	A
		$T_c=100^\circ C$	A
$I_{DM}$	Pulse drain current tested ①	$T_c=25^\circ C$	A
EAS	Avalanche energy, single pulsed ②	256	mJ
$P_D$	Maximum power dissipation	$T_c=25^\circ C$	W
$V_{GS}$	Gate-Source voltage	$\pm 20$	V
$T_{STG} T_J$	Storage and operating temperature range	-55 to 175	°C

## Thermal Characteristics

Symbol	Parameter	Typical	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	2.5	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	60	°C/W

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
<b>Static Electrical Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	60	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(T <sub>c</sub> =25°C)	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T <sub>c</sub> =125°C)	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V	--	--	100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	1	2	3	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =50A	--	7.0	10.0	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>③</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A	--	8.0	14.0	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1MHz	--	3310	--	pF
C <sub>oss</sub>	Output Capacitance		--	740	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	290	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =55V, I <sub>D</sub> =30A, V <sub>GS</sub> =10V	--	48	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	12	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	10	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =30V, I <sub>D</sub> =1A, R <sub>G</sub> =6.8Ω, V <sub>GS</sub> =10V	--	15	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	13	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	27	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	22	--	nS
<b>Source- Drain Diode Characteristics@ T<sub>c</sub> = 25°C (unless otherwise stated)</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =20A, V <sub>GS</sub> =0V	--	0.81	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>j</sub> =25°C, I <sub>SD</sub> =20A, V <sub>GS</sub> =0V di/dt=100A/μs	--	62	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge		--	80	--	nC

## NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Limited by T<sub>Jmax</sub>, starting T<sub>j</sub> = 25°C, L = 0.5mH, R<sub>G</sub> = 25Ω, I<sub>AS</sub> = 28A, V<sub>GS</sub> = 10V. Part not recommended for use above this value

③ Pulse width ≤ 300μs; duty cycles≤ 2%.

## Typical Characteristics

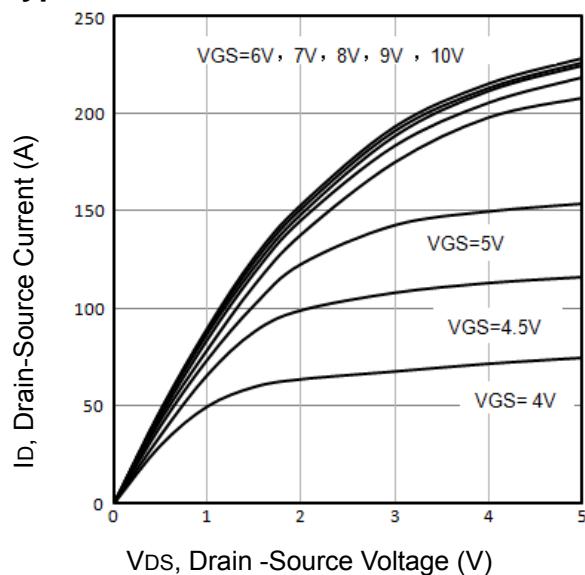


Fig1. Typical Output Characteristics

**VS6065AD**  
60V/65A N-Channel Advanced Power MOSFET

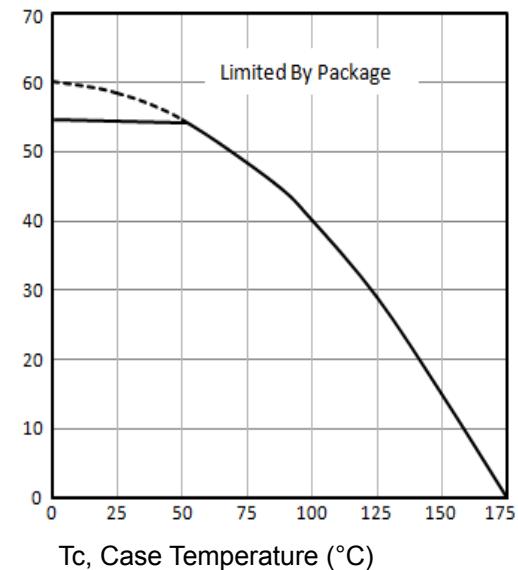


Fig2. Maximum Drain Current Vs. Case Temperature

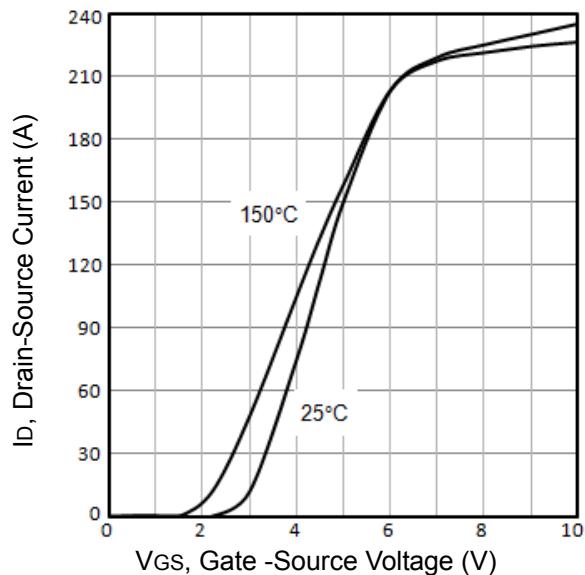


Fig3. Typical Transfer Characteristics

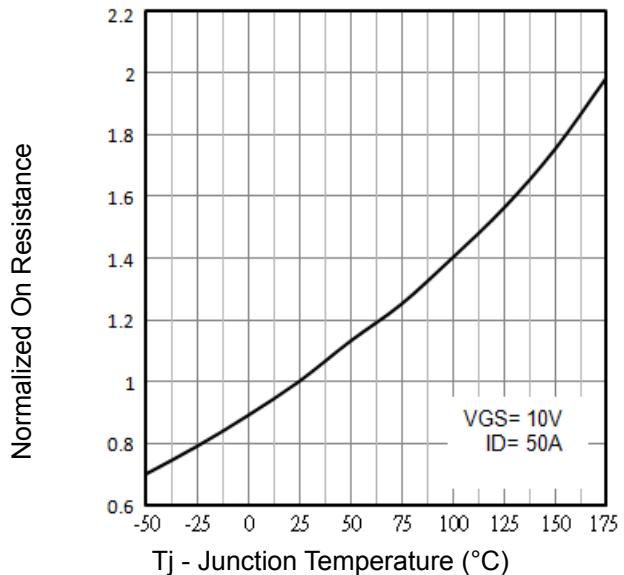


Fig4. Normalized On-Resistance Vs.  $T_j$

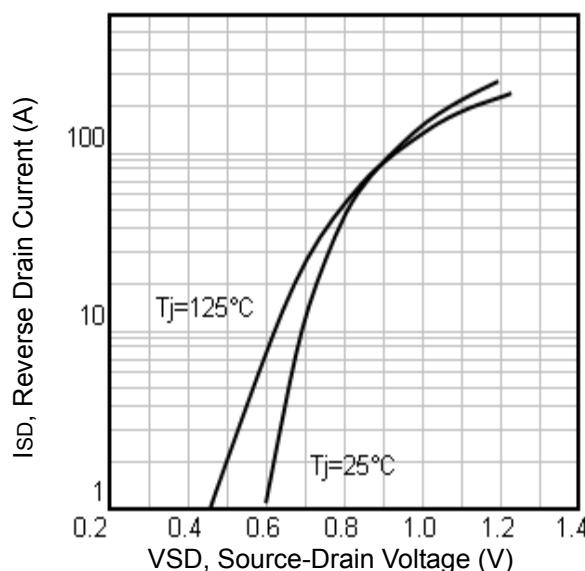


Fig5. Typical Source-Drain Diode Forward Voltage

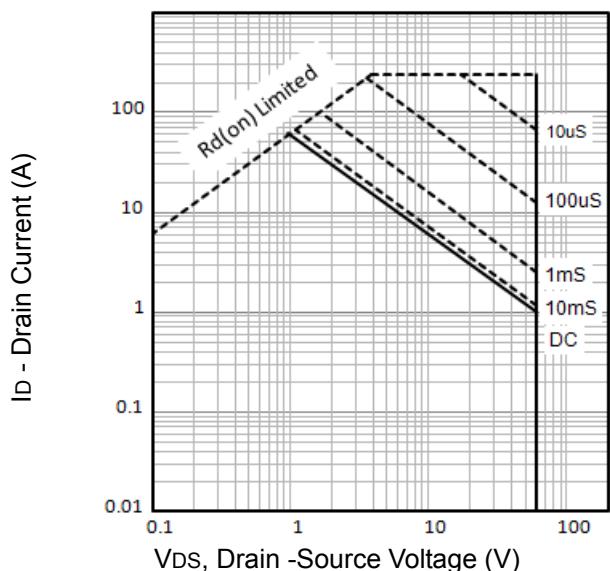


Fig6. Maximum Safe Operating Area

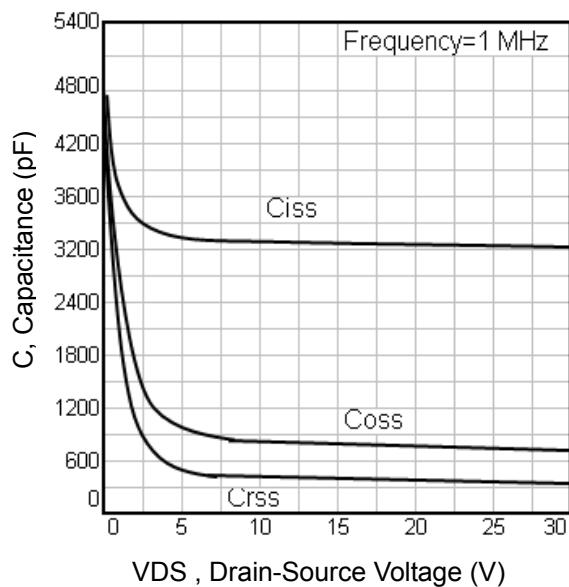


Fig7. Typical Capacitance Vs.Drain-Source

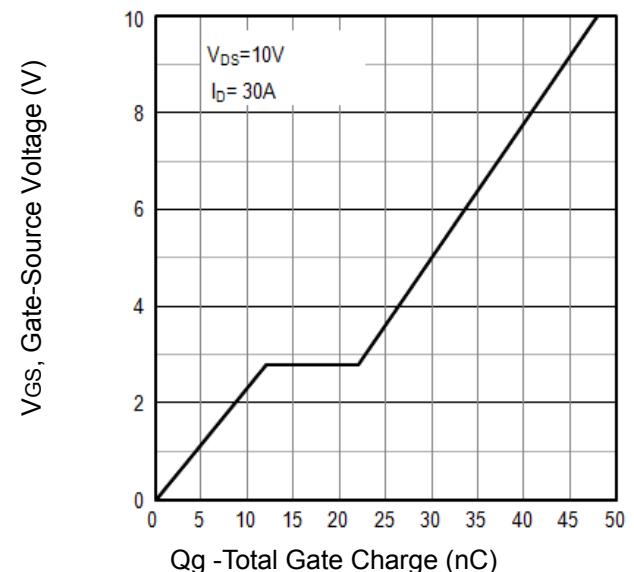


Fig8. Typical Gate Charge Vs.Gate-Source

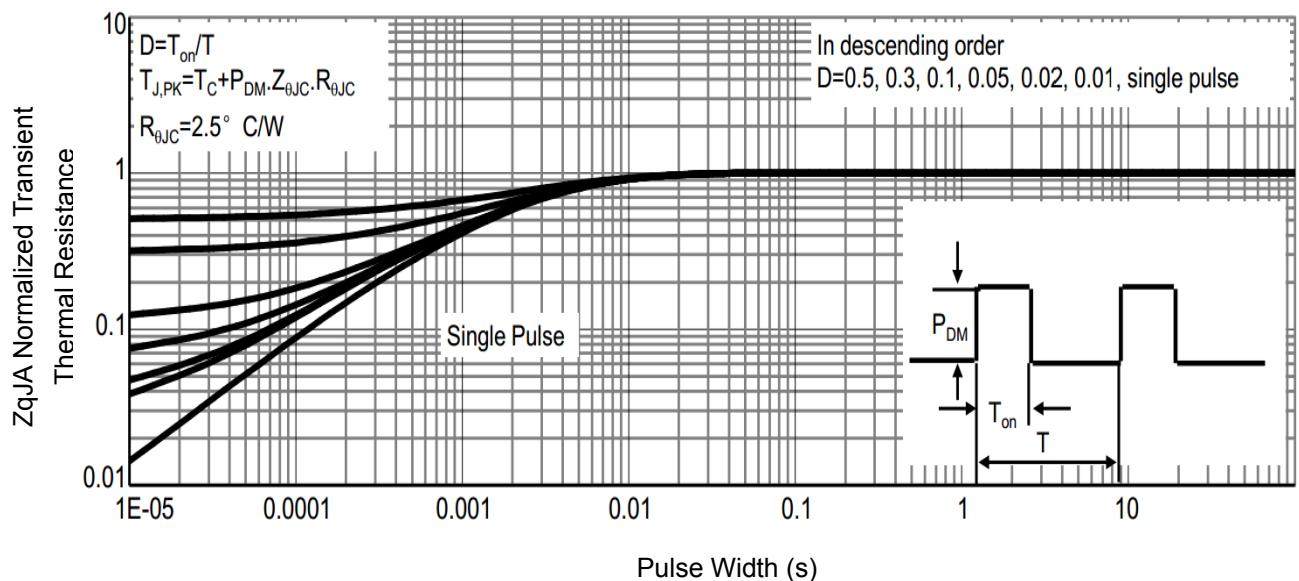


Figure 9: Normalized Maximum Transient Thermal

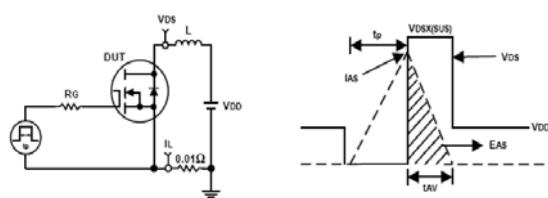


Fig10. Unclamped Inductive Test Circuit and waveforms

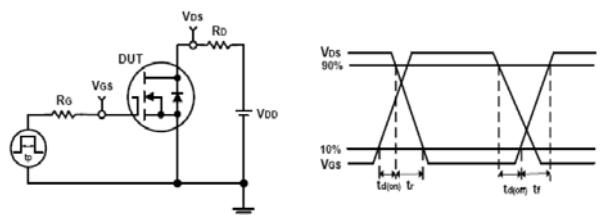
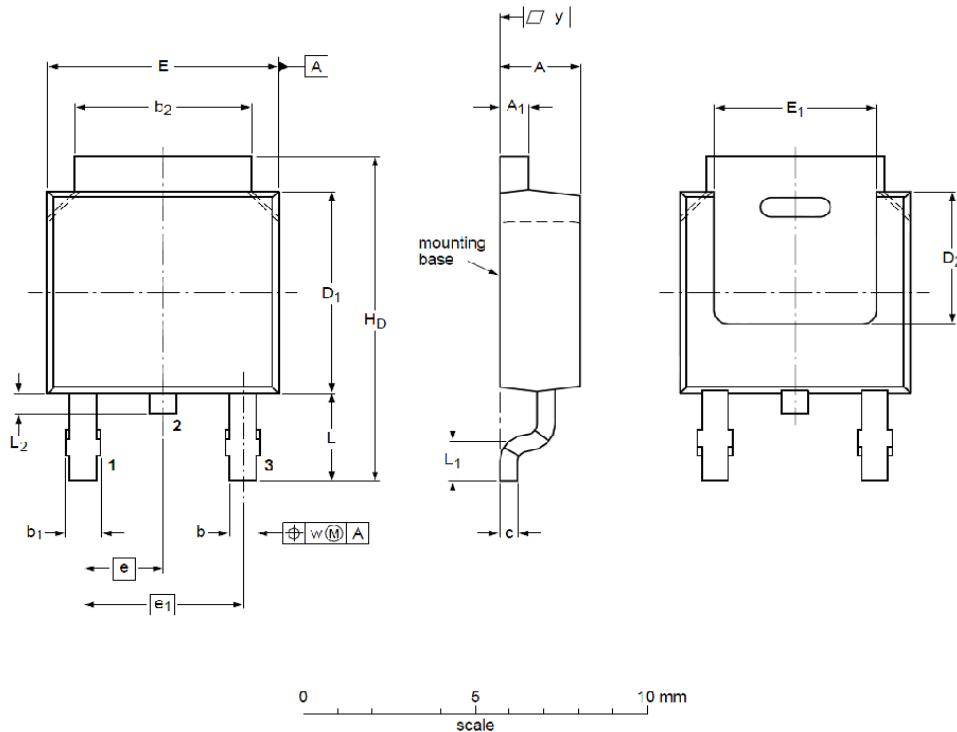


Fig11. Switching Time Test Circuit and waveforms

## TO-252 Package Outline



**DIMENSIONS ( unit : mm )**

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
<b>A</b>	2.22	2.30	2.38	<b>A<sub>1</sub></b>	0.46	0.58	0.93
<b>b</b>	0.71	0.79	0.89	<b>b<sub>1</sub></b>	0.90	0.98	1.10
<b>b<sub>2</sub></b>	5.00	5.30	5.46	<b>c</b>	0.20	0.40	0.56
<b>D<sub>1</sub></b>	5.98	6.05	6.22	<b>D<sub>2</sub></b>	--	4.00	--
<b>E</b>	6.47	6.60	6.73	<b>E<sub>1</sub></b>	5.10	5.28	5.45
<b>e</b>	--	2.28	--	<b>e<sub>1</sub></b>	--	4.57	--
<b>H<sub>b</sub></b>	9.60	10.08	10.40	<b>L</b>	2.75	2.95	3.05
<b>L<sub>1</sub></b>	--	0.50	--	<b>L<sub>2</sub></b>	0.80	0.90	1.10
<b>w</b>	--	0.20	--	<b>y</b>	0.20	--	--

## Customer Service

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